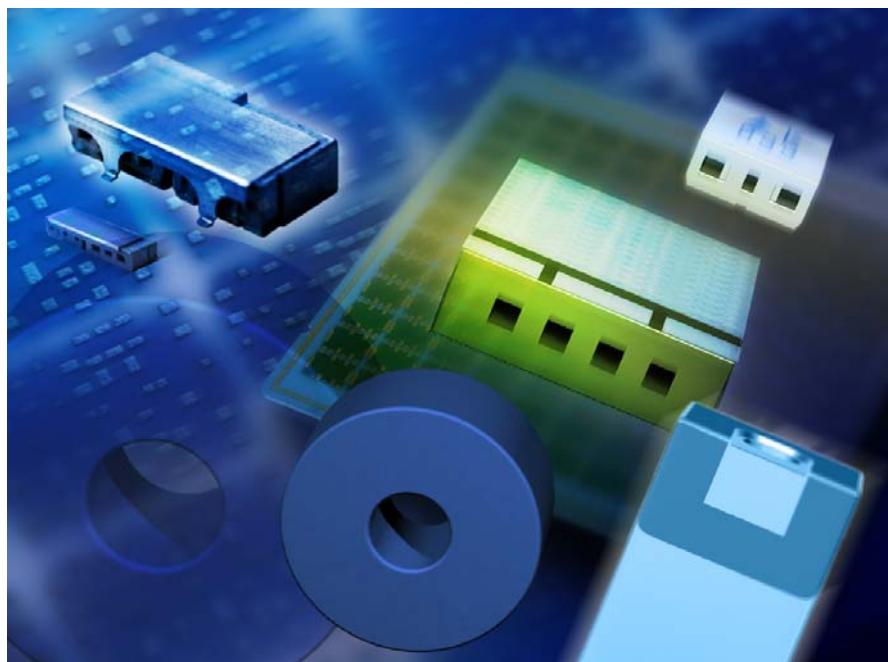


Datasheet



Features

- Low Profile (maximum height 1.4 mm)
- SMD filter consisting of coupled resonators with stepped impedances
- Low losses
- High attenuations at GSM (900, 1800) and UMTS bands
- High attenuation at 2 times center frequency
- (NdBa)TiO₃ ($\epsilon_r = 88$ / $TC_f = 0 \pm 10$ ppm/K) with a coating of copper (10 μ m) and tin (>5 μ m)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

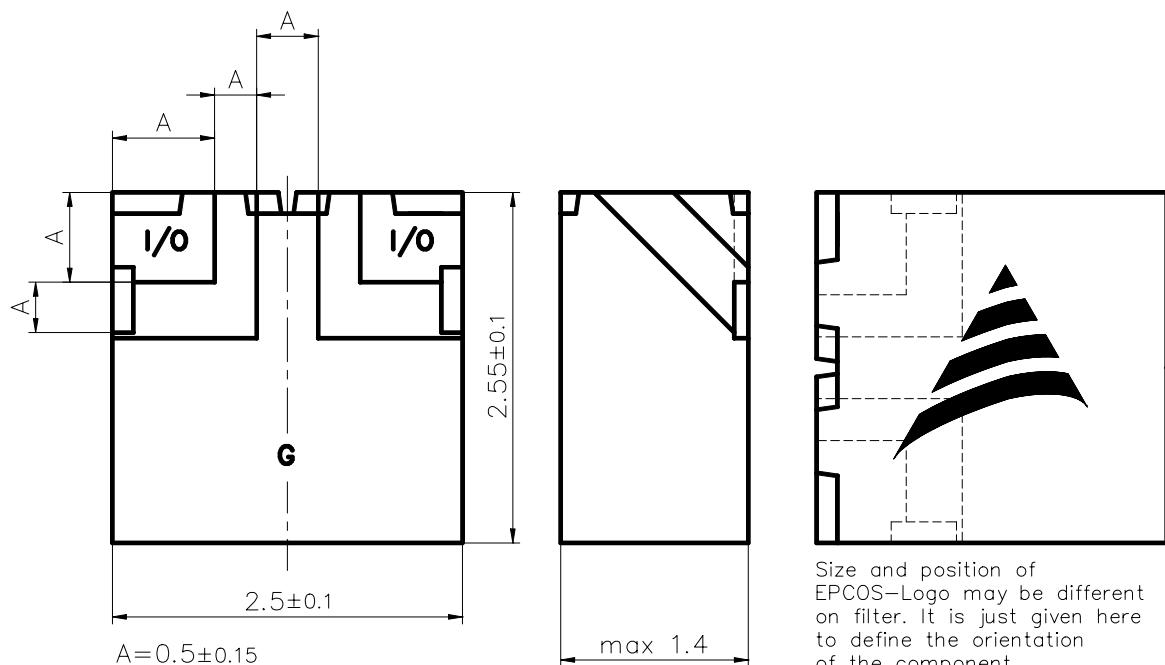
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Page 4	<ul style="list-style-type: none">• Processing information• Soldering requirements• Delivery mode

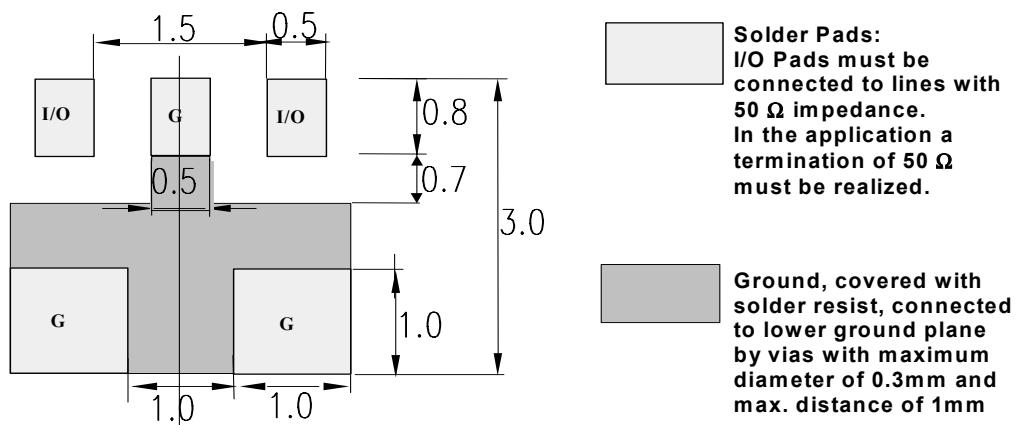
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Dimension Limits , Marking



Recommended footprint

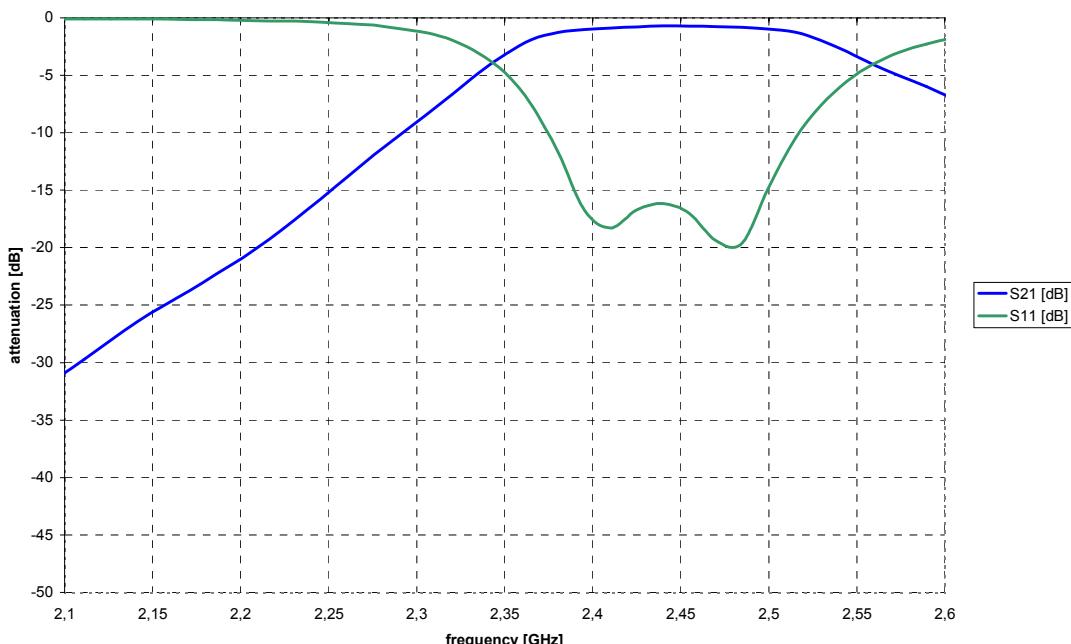


Datasheet
Characteristics

		min.	typ.	max.	
Center frequency	f_c	-	2.450	-	GHz
Insertion loss	α_{IL}		1.4	1.8	dB
Passband (2400- 2500)	B	100			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.4	0.8	dB
Standing wave ratio	SWR		1.5	2.0	
Impedance	Z		50		Ω
Attenuation	α				
at DC to 827 MHz		56	60		dB
at 880 to 960 MHz		48	55		dB
at 1710 to 1910 MHz		45	47		dB
at 1930 to 1990 MHz		48	49		dB
at 1990 to 2100 MHz		30	34		dB
at 2100 to 2170 MHz		23	27		dB
at 3200 to 3500 MHz		28	30		dB
at 4000 to 4600 MHz		27	30		dB
at 4800 to 5000 MHz		25	30		dB
at 5600 to 5789 MHz		15	20		dB
at 6400 to 6615 MHz		5	10		dB

Maximum ratings

IEC climatic category (IEC 68-1)	- 40 / + 90/56	
Operating temperature	T_{op} - 40 / + 85	°C

Typical passband characteristics


Datasheet

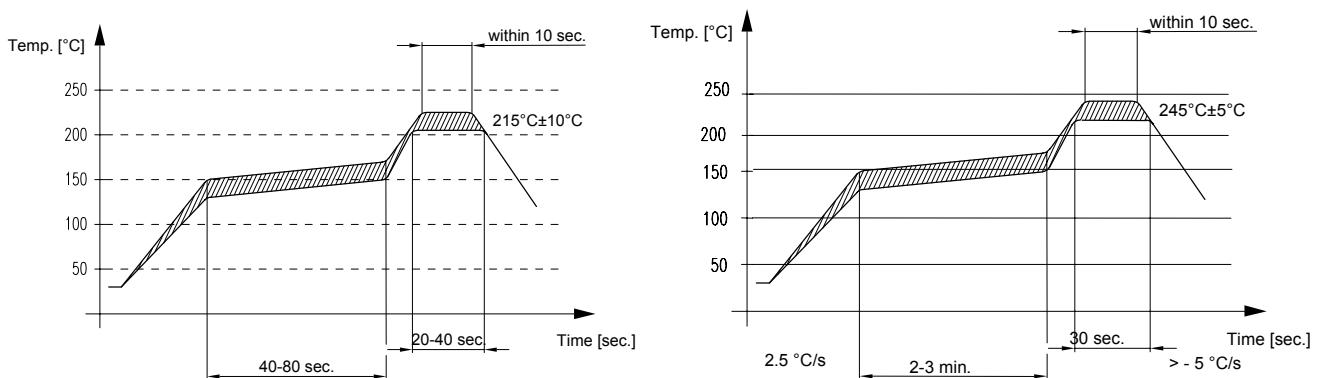
Processing information

- Wettability to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

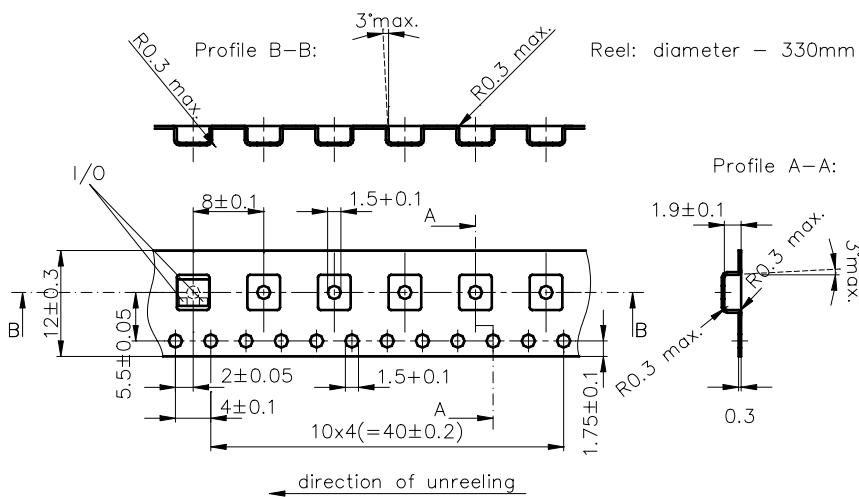
	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape acc. to IEC 286-3, grey
- Pieces/tape: 4000



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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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